

## **General Description**

The WSD30150DN56 is the highest performance trench N-Ch MOSFET with extreme high celldensity ,which provide excellent  $R_{\text{DSON}}$  and gate charge for most of the synchronous buck converter applications .

The WSD30150DN56 meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

#### **Features**

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% EAS Guaranteed
- Green Device Available

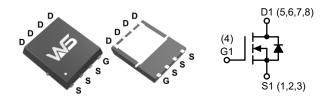
## **Product Summery**

BV <sub>DSS</sub>	R <sub>DSON</sub>	I <sub>D</sub>
30V	1.8mΩ	150A

## **Applications**

- High Frequency Point-of-Load Synchronous Buck Converter
- Networking DC-DC Power System
- Power Tool Application

## **DFN5X6-8L Pin Configuration**



## **Absolute Maximum Ratings**

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	30	V
$V_{GS}$	Gate-Source Voltage	±20	V
I <sub>D</sub> @T <sub>C</sub> =25℃	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1,7</sup>	150	Α
I <sub>D</sub> @T <sub>C</sub> =100℃	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1,7</sup>	83	А
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup>	200	А
EAS	Single Pulse Avalanche Energy <sup>3</sup>	125	mJ
I <sub>AS</sub>	Avalanche Current	50	Α
P <sub>D</sub> @T <sub>C</sub> =25°C	Total Power Dissipation <sup>4</sup>	62.5	W
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	$^{\circ}$
TJ	Operating Junction Temperature Range	-55 to 150	$^{\circ}$

#### **Thermal Data**

Symbol	Parameter		Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient <sup>1</sup>		30	°C/W
$R_{ heta JC}$	Thermal Resistance Junction-Case <sup>1</sup>		2	°C/W



## Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =250uA	30			V
$\triangle BV_{DSS}/\triangle T_{J}$	BV <sub>DSS</sub> Temperature Coefficient	Reference to 25 $^{\circ}\mathrm{C}$ , I <sub>D</sub> =1mA		0.02		V/℃
В	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =10V , I <sub>D</sub> =20A		1.8	2.4	mO
R <sub>DS(ON)</sub>		V <sub>GS</sub> =4.5V , I <sub>D</sub> =15A		2.4	3.2	mΩ
V <sub>GS(th)</sub>	Gate Threshold Voltage	)/ -\/   -250A	1.4	1.7	2.5	V
$\triangle V_{GS(th)}$	V <sub>GS(th)</sub> Temperature Coefficient	$V_{GS}=V_{DS}$ , $I_D=250uA$		-6.1		mV/℃
	Dunin Course Legisone Cumunt	V <sub>DS</sub> =24V , V <sub>GS</sub> =0V , T <sub>J</sub> =25℃			1	- uA
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =24V , V <sub>GS</sub> =0V , T <sub>J</sub> =55℃			5	
I <sub>GSS</sub>	Gate-Source Leakage Current	$V_{GS}$ = $\pm 20V$ , $V_{DS}$ = $0V$			±100	nA
gfs	Forward Transconductance	V <sub>DS</sub> =5V , I <sub>D</sub> =10A		27		S
Rg	Gate Resistance	V <sub>DS</sub> =0V , V <sub>GS</sub> =0V , f=1MHz		0.8	1.5	Ω
$Q_g$	Total Gate Charge (4.5V)	V <sub>DS</sub> =15V , V <sub>GS</sub> =4.5V , I <sub>D</sub> =30A		26		nC
$Q_gs$	Gate-Source Charge			9.5		
Q <sub>gd</sub>	Gate-Drain Charge			11.4		
T <sub>d(on)</sub>	Turn-On Delay Time			20		
T <sub>r</sub>	Rise Time	$V_{DD}$ =15V , $V_{GEN}$ =10V , $R_{G}$ =6 $\Omega$ , $I_{D}$ =1A, $RL$ =15 $\Omega$ .		12		no
T <sub>d(off)</sub>	Turn-Off Delay Time			69		ns
T <sub>f</sub>	Fall Time			29		
Ciss	Input Capacitance		2560	3200	3850	
C <sub>oss</sub>	Output Capacitance	V <sub>DS</sub> =15V , V <sub>GS</sub> =0V , f=1MHz	560	680	800	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		260	320	420	

### **Guaranteed Avalanche Characteristics**

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
EAS	Single Pulse Avalanche Energy <sup>5</sup>	V <sub>DD</sub> =25V , L=0.1mH , I <sub>AS</sub> =30A	98			mJ

#### **Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
I <sub>S</sub>	Continuous Source Current <sup>1,6</sup>	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current			30	Α
I <sub>SM</sub>	Pulsed Source Current <sup>2,6</sup>	V <sub>G</sub> -V <sub>D</sub> -UV , Force Current			200	Α
V <sub>SD</sub>	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V , I <sub>S</sub> =A , T <sub>J</sub> =25℃			1.2	V

### Note:

- 1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper, t<10 sec.
- 2.The data tested by pulsed , pulse width  $\leq$  300us , duty cycle  $\leq$  2%
- 3. The EAS data shows Max. rating . The test condition is  $V_{DD}$ =25V,  $V_{GS}$ =10V, L=0.1mH,  $I_{AS}$ =30A
- 4.The power dissipation is limited by 150  $^{\circ}\mathrm{C}$  junction temperature
- 5.The Min. value is 100% EAS tested guarantee.
- 6. The data is theoretically the same as  $I_D$  and  $I_{DM}$ , in real applications, should be limited by total power dissipation.
- 7.Package limitation current is 100A.



## **Typical Characteristics**

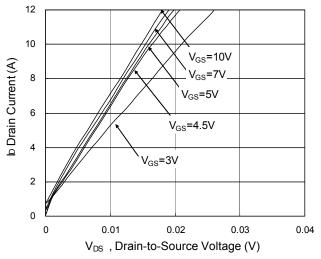


Fig.1 Typical Output Characteristics

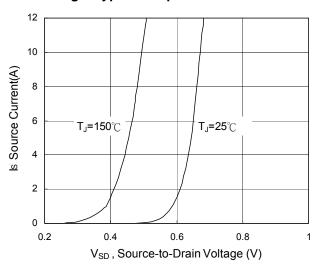


Fig.3 Forward Characteristics of Reverse

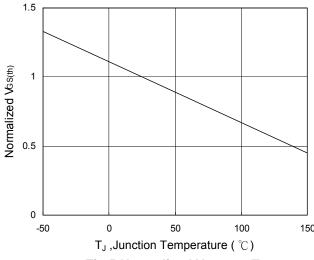


Fig.5 Normalized V<sub>GS(th)</sub> v.s T<sub>J</sub>

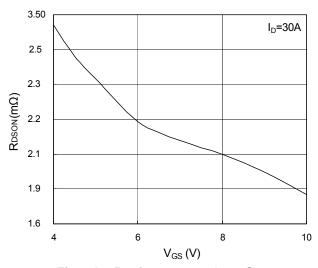


Fig.2 On-Resistance v.s Gate-Source

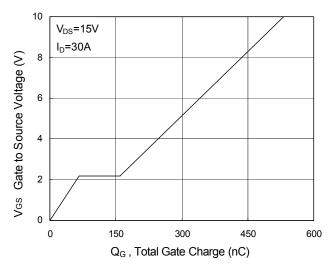


Fig.4 Gate-Charge Characteristics

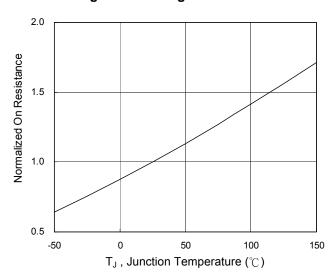
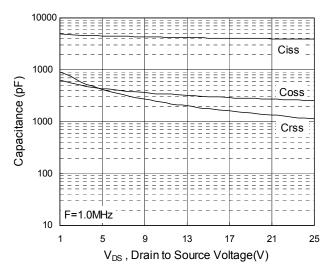


Fig.6 Normalized R<sub>DSON</sub> v.s T<sub>J</sub>





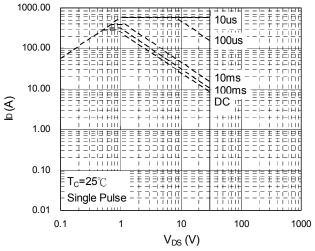


Fig.7 Capacitance

Fig.8 Safe Operating Area

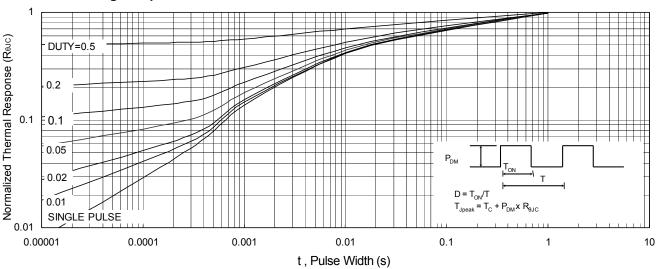


Fig.9 Normalized Maximum Transient Thermal Impedance

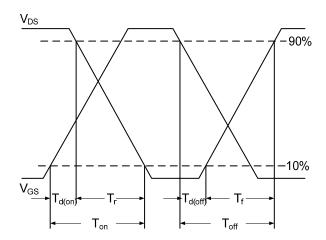


Fig.10 Switching Time Waveform

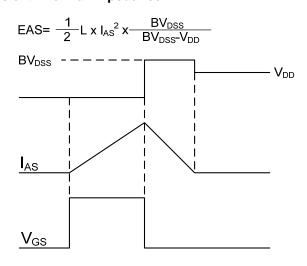
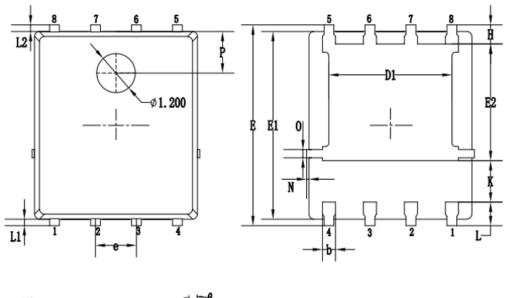
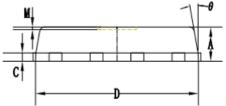


Fig.11 Unclamped Inductive Waveform



# **Packaging information**





CVMDOLC	MILLIMETERS				
SYMBOLS	MIN.	NOM.	MAX.		
Α	0.90	1.05	1.20		
b	0.35	0.40	0.50		
С	0.20	0.25	0.35		
D	4.90	5.05	5.20		
D1	3.72	3.82	3.92		
E	6.00	6.15	6.30		
E1	5.60	5.75	5.90		
E2	3.47	3.57	3.67		
е		1.27 BSC.			
Н	0.48	0.58	0.68		
K	1.17	1.27	1.37		
L	0.64	0.74	0.84		
L1/L2		0.20 REF.			
θ	8°	10°	12°		
М		0.08 REF.			
N	0	-	0.15		
0		0.25 REF.			
Р		1.28 REF.			



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